

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT	
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT	
<b>CONVEYING PARTY DATA</b>		
	<b>Name</b>	<b>Execution Date</b>
	HISASHI KITAGAWA	11/19/2018
	YOSHIYUKI OOMASA	10/29/2018
	HIDEKI SHUDAI	10/29/2018
	YOSHIHIKO UENO	10/29/2018
	DAISUKE MIYAZAKI	10/31/2018
	MASATO TAKEDA	10/29/2018
	TOSHINORI OHTOMO	11/20/2018
	TOSHIKAZU KAMAE	10/29/2018
<b>RECEIVING PARTY DATA</b>		
<b>Name:</b>	MAYEKAWA MFG. CO., LTD.	
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<b>State/Country:</b>	JAPAN	
<b>Postal Code:</b>	1358482	
<b>PROPERTY NUMBERS Total: 1</b>		
	<b>Property Type</b>	<b>Number</b>
	Application Number:	16313158
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<b>ATTORNEY DOCKET NUMBER:</b>	83196-US-1325-PCT	
<b>NAME OF SUBMITTER:</b>	BELINDA LEE	
<b>SIGNATURE:</b>	/Belinda Lee/	

<b>DATE SIGNED:</b>	12/26/2018
<b>Total Attachments: 3</b> source=83196_asm#page1.tif source=83196_asm#page2.tif source=83196_asm#page3.tif	

## ASSIGNMENT

WHEREAS,

- |                     |                     |
|---------------------|---------------------|
| 1. Hisashi KITAGAWA | 2. Yoshiyuki OOMASA |
| 3. Hideki SHUDAI    | 4. Yoshihiko UENO   |
| 5. Daisuke MIYAZAKI | 6. Masato TAKEDA    |
| 7. Toshinori OHTOMO | 8. Toshikazu KAMAE  |

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **WELDING DEVICE AND WELDING METHOD**

[ ] Filed: Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, **MAYEKAWA MFG. CO., LTD.**  
of 14-15, Botan 3-chome, Koto-ku, Tokyo 1358482 JAPAN

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

## ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Hisashi Kitagawa

First Joint Inventor: Hisashi KITAGAWA

Date: 11.19.2018

Signature: Yoshiyuki - Oomasa

Second Joint Inventor: Yoshiyuki OOMASA

Date: 10.29.2018

Signature: Hideki - SHUDA /

Third Joint Inventor: Hideki SHUDAI

Date: 10.29.2018

Signature: Yoshihiko Ueno

Fourth Joint Inventor: Yoshihiko UENO

Date: 10.29.2018

Signature: Daisuke Miyazaki

Fifth Joint Inventor: Daisuke MIYAZAKI

Date: 10.31.2018

Signature: Masato Takeda

Sixth Joint Inventor: Masato TAKEDA

Date: 10.29.2018

Signature: Toshinori Ohtomo

Seventh Joint Inventor: Toshinori OHTOMO

Date: 11.20.2018

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Signature: Toshikazu Kamae

Date: 10.29.2018

Eighth Joint Inventor: Toshikazu KAMAE